

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): A method of depositing a silicon-containing film on a substrate, the method comprising:

providing a substrate in a process chamber of a processing system;

heating the substrate;

exposing a HCD process gas to the substrate; and

depositing a silicon~~[[-]]~~containing~~ or silicon-germanium film on the substrate using the HCD process gas.~~

Claim 2 (Original): The method according to claim 1, wherein the exposing comprises exposing an inert gas to the substrate.

Claim 3 (Currently Amended): The method according to claim 2, wherein the exposing further comprises flowing ~~a~~the HCD gas at a flow rate between about 5_sccm and about 1,000_sccm and the inert gas at a flow rate between about 5_sccm and about 20,000 sccm.

Claim 4 (Original): The method according to claim 1, wherein the exposing further comprises exposing a hydrogen-containing gas to the substrate.

Claim 5 (Original): The method according to claim 1, wherein the exposing further comprises exposing H₂ to the substrate.

Claim 6 (Currently Amended): The method according to claim 1, wherein the ~~flowing~~ exposing further comprises flowing a hydrogen-containing gas at a flow rate between about 5_sccm and about 5,000_sccm.[[.]]

Claim 7 (Original): The method according to claim 1, wherein the exposing further comprises exposing a second silicon-containing gas to the substrate.

Claim 8 (Original): The method according to claim 1, wherein the exposing further comprises exposing at least one of SiH₄, SiCl₄, Si₂H₆, and SiH₂Cl₂ to the substrate.

Claim 9 (Currently Amended): The method according to claim 3, wherein the ~~flowing~~ exposing further comprises flowing a second silicon-containing gas at a flow rate between about 5_sccm and about 1,000_sccm.

Claim 10 (Original): The method according to claim 1, wherein the exposing further comprises exposing a hydrogen-containing gas and a second silicon-containing gas to the substrate.

Claim 11 (Original): The method according to claim 1, wherein the exposing further comprises exposing H₂ and at least one of SiH₄, SiCl₄, Si₂H₆, and SiH₂Cl₂ to the substrate.

Claim 12 (Original): The method according to claim 1, wherein the exposing further comprises exposing a HCD gas and at least one of a phosphor-containing gas, a boron-containing gas, and a nitrogen-containing gas to the substrate.

Claim 13 (Currently Amended): The method according to claim 1, wherein the exposing further comprises exposing a HCD gas and at least one of PH_3 , B_2H_6 , BCl_3 , and NH_3 AsH_3 to the substrate.

Claim 14 (Original): The method according to claim 1, wherein the exposing further comprises exposing a halogen-containing gas to the substrate.

Claim 15 (Original): The method according to claim 1, wherein the exposing further comprises exposing at least one of HF , F_2 , Cl_2 , and HCl to the substrate.

Claim 16 (Original): The method according to claim 1, wherein the exposing further comprises exposing a germanium-containing gas to the substrate.

Claim 17 (Currently Amended): The method according to claim 16, wherein the exposing further comprises exposing $[[a]]$ at least one of a hydrogen-containing gas, a dopant gas, and a halogen-containing gas to the substrate.

Claim 18 (Original): The method according to claim 1, wherein the exposing further comprises exposing at least one of GeH_4 and GeCl_4 to the substrate.

Claim 19 (Original): The method according to claim 1, wherein the exposing further comprises exposing a hydrogen-containing gas and a germanium-containing gas to the substrate.

Claim 20 (Original): The method according to claim 1, wherein the exposing further comprises exposing H_2 and GeH_4 to the substrate.

Claim 21 (Currently Amended): The method according to claim 1, wherein the depositing comprises selectively depositing an epitaxial silicon or silicon-germanium ~~[[-]]~~ containing film on a silicon substrate.

Claim 22 (Currently Amended): The method according to claim 1, wherein the depositing comprises non-selectively depositing a polycrystalline ~~silicon~~ ~~[[-]]~~ containing film or an amorphous silicon or silicon-germanium ~~[[-]]~~ containing film on a substrate.

Claim 23 (Currently Amended): The method according to claim 1, wherein the exposing comprises exposing a HCD process gas including HCD gas and a germanium-containing gas to the substrate; and the depositing comprises depositing a ~~SiGe~~ ~~[[-]]~~ containing film on the substrate.

Claim 24 (Currently Amended): The method according to claim 23, wherein the depositing comprises selectively depositing a ~~SiGe~~ ~~[[-]]~~ containing film on a silicon surface.

Claim 25 (Currently Amended): The method according to claim 23, wherein the depositing comprises depositing a ~~SiGe~~ ~~[[-]]~~ containing film having a germanium content below about two atomic percent.

Claim 26 (Currently Amended): The method according to claim 23, wherein the depositing comprises depositing a SiGe~~[[-]]~~~~containing~~ film having a germanium content greater than about two atomic percent.

Claim 27 (Original): The method according to claim 1, wherein the heating comprises heating the substrate to between about 500°C and about 900°C.

Claim 28 (Original): The method according to claim 1, wherein the heating comprising heating the substrate to between about 700°C and about 900°C.

Claim 29 (Currently Amended): The method according to claim 1, wherein the heating comprises heating the substrate to a temperature of about 800°C and the depositing comprises selectively depositing an epitaxial silicon or silicon-germanium~~[[-]]~~~~containing~~ film on a silicon surface of the substrate.

Claim 30 (Currently Amended): The method according to claim 1, wherein the heating comprises heating the substrate to a temperature of about 700°C and the depositing comprises non-selectively depositing a the silicon or silicon-germanium~~[[-]]~~~~containing~~ film on the substrate.

Claim 31 (Currently Amended): The method according to claim 1, further comprising providing a process chamber pressure less than about 100 Torr.

Claim 32 (Currently Amended): The method according to claim 1, further comprising providing a process chamber pressure less than about 10 Torr.

Claim 33 (Currently Amended): The method according to claim 1, further comprising providing a process chamber pressure of about 0.4 Torr.

Claim 34 (Original): The method according to claim 1, further comprising:
pretreating the substrate prior to exposing a HCD process gas to the substrate.

Claim 35 (Original): The method according to claim 34, wherein the pretreating comprises exposing a H₂ gas to the substrate at a substrate temperature between about 500°C and about 1000°C.

Claim 36 (Original): The method according to claim 34, wherein the pretreating comprises exposing a H₂ gas to the substrate at a substrate temperature of about 900°C.

Claim 37 (Original): A computer readable medium containing program instructions for execution on a processor, which when executed by the processor, cause a processing apparatus to perform the steps in the method recited in claim 1.

Claim 38 (Currently Amended): A system for processing a substrate, comprising:
means for providing a substrate in a process chamber of a processing system;
means for heating the substrate;
means for exposing a HCD process gas to the substrate to deposit a silicon[[-
]]~~containing~~ or silicon-germanium film on the substrate.

Claim 39 (Currently Amended): A processing tool for depositing a silicon~~[[-~~
~~]]containing~~ or silicon-germanium film on a substrate comprising:

- a processing system;
- a transfer system configured to provide the substrate in a process chamber of the processing system;
- a heater for heating the substrate;
- a gas injection system configured to expose a HCD process gas to the substrate in the processing system to form a silicon or silicon-germanium film on the substrate; and
- a controller configured to control the processing tool.

Claim 40 (Original): The processing tool according to claim 39, wherein the processing system comprises a batch type processing system or a single wafer processing system.

Claim 41 (Original): The processing tool according to claim 39, wherein the processing system comprises a batch type processing system containing a process tube.

Claim 42 (Original): The processing tool according to claim 39, wherein the processing system comprises a thermal processing system, a plasma processing system, or an atomic layer deposition system.

Claim 43 (Original): The processing tool according to claim 39, further comprising a processing system configured for pretreating the substrate.

Claim 44 (Original): The processing tool according to claim 39, further comprising a process monitoring system.

Claim 45 (Original): The processing tool according to claim 39, wherein the gas injection system is configured to expose a HCD process gas comprising HCD and an inert gas and at least one of a hydrogen-containing gas, a silicon-containing gas, and a germanium-containing gas to the substrate.

Claim 46 (Original): The processing tool according to claim 40, wherein the gas injection system is configured to expose a HCD process gas comprising HCD and an inert gas and at least one of a dopant gas and a halogen-containing gas to the substrate.

Claim 47 (New): The method according to claim 1, wherein the depositing comprises selectively depositing an epitaxial Si film on a crystalline Si substrate.

Claim 48 (New): The method according to claim 1, wherein the depositing comprises selectively depositing an epitaxial Si film on a crystalline SiGe substrate.

Claim 49 (New): The method according to claim 1, wherein the depositing comprises selectively depositing an epitaxial SiGe film on a crystalline Si substrate.

Claim 50 (New): The method according to claim 1, wherein the depositing comprises selectively depositing an epitaxial SiGe film on a crystalline SiGe substrate.

Claim 51 (New): A method of depositing a silicon-containing film on a substrate, the method comprising:

providing a substrate in a process chamber of a processing system;

heating the substrate;

exposing a HCD process gas to the substrate; and

depositing a silicon-containing non-insulating film on the substrate using the HCD process gas.